

Abstract

A process for the copper plating of substrates using insoluble anodes in acidic copper baths with separate replenishing of consumed copper ions, characterized in that the major portion of the copper ions is directly supplied in the form of copper carbonate and/or basic copper carbonate, dispensing with diaphragms and auxiliary electrolytes, in a separate tank operated in a bypass mode with respect to the working electrolyte, the released gaseous CO₂ being separated off in said separate tank.